

HAT1111C

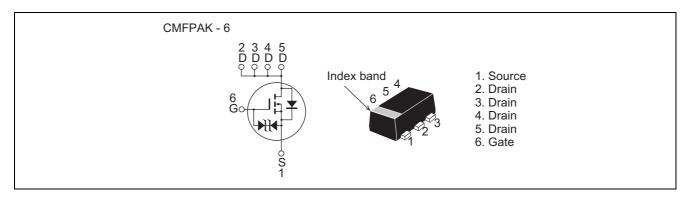
Silicon P Channel MOS FET Power Switching

REJ03G0446-0500 Rev.5.00 Oct.19.2004

Features

- Low on-resistance $R_{DS(on)} = 245 \ m\Omega \ typ. \ (at \ V_{GS} = -10V)$
- Low drive current.
- 4.5 V gate drive devices.
- High density mounting

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to Source voltage	V_{DSS}	-60	V
Gate to Source voltage	V_{GSS}	-20 / +10	V
Drain current	I _D	-2	А
Drain peak current	I _D (pulse) ^{Note1}	-8	А
Body - Drain diode reverse drain current	I _{DR}	-2	А
Channel dissipation	Pch ^{Note 2}	1.25	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. When using the glass epoxy board. (FR4 $40 \times 40 \times 1.6$ mm), PW ≤ 5 s, Ta = 25° C

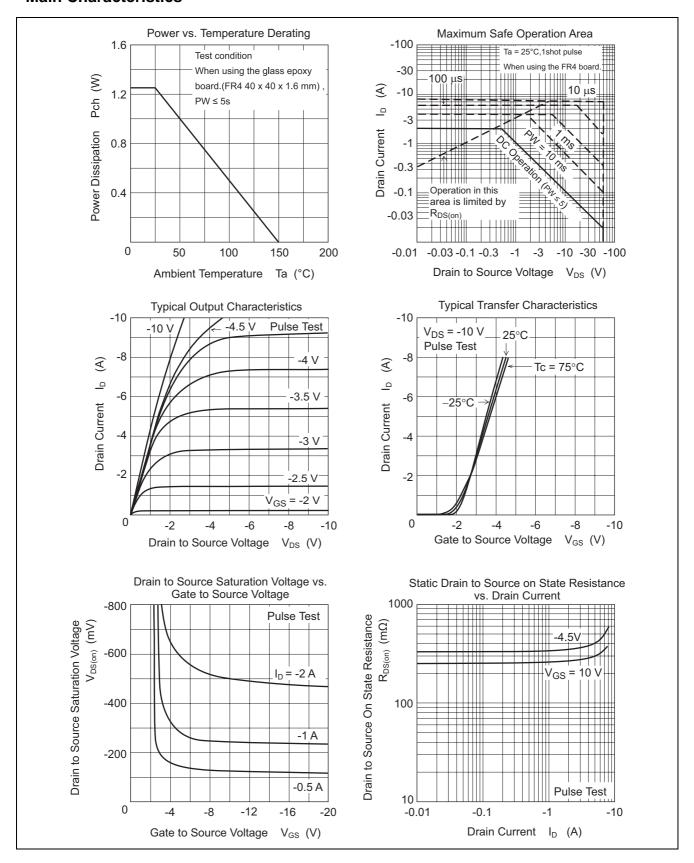
Electrical Characteristics

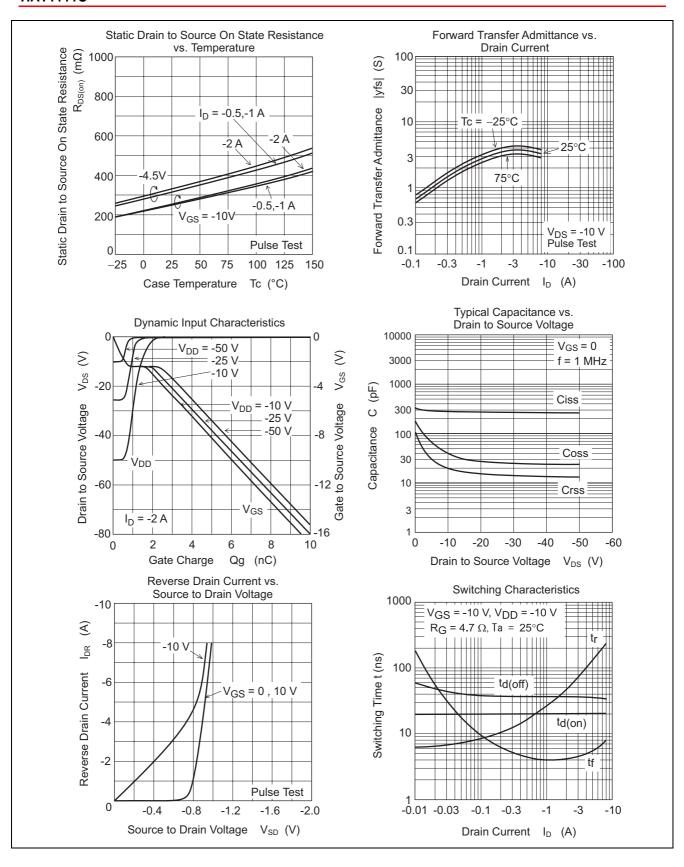
 $(Ta = 25^{\circ}C)$

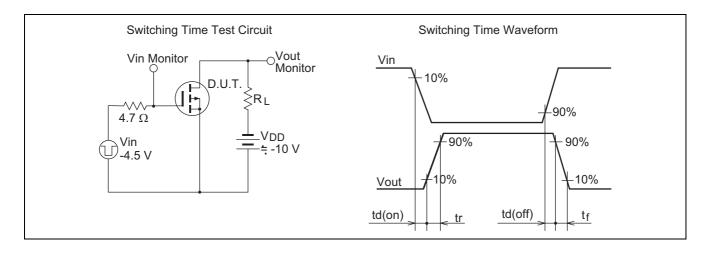
Item	Symbol	Min.	Тур.	Max.	Unit	Test Conditions	
Drain to Source breakdown voltage	$V_{(BR)DSS}$	-60	_	_	V	$I_D = -10 \text{ mA}, V_{GS} = 0$	
Gate to Source breakdown voltage	$V_{(BR)GSS}$	-20	_	_	V	$I_G = \pm 100 \mu\text{A}, V_{DS} = 0$	
		+10					
Gate to Source leakage current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = -16 / +8 V, V_{DS} = 0$	
Drain to Source leakage current	I _{DSS}	_	_	-1	μΑ	$V_{DS} = -60 \text{ V}, V_{GS} = 0$	
Gate to Source cutoff voltage	$V_{GS(th)}$	-1	_	-2	V	$I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}^{\text{Note3}}$	
Drain to Source on state resistance	R _{DS(on)}	_	245	307	mΩ	$I_D = -1 \text{ A}, V_{GS} = -10 \text{ V}^{\text{Note3}}$	
		_	310	450	mΩ	$I_D = -1 \text{ A}, V_{GS} = -4.5 \text{ V}^{\text{Note3}}$	
Forward transfer admittance	y _{fs}	0.65	1	1	S	$I_D = -1 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note3}}$	
Input capacitance	Ciss	_	290	_	pF	$V_{DS} = -10 \text{ V}, V_{GS} = 0$	
Output capacitance	Coss	_	40	_	pF	f = 1 MHz	
Reverse transfer capacitance	Crss	_	20	_	pF		
Total gate charge	Qg	_	6	_	nC	$V_{DS} = -10 \text{ V}, V_{GS} = -10 \text{ V}$	
Gate to Source charge	Qgs	_	0.7	_	nC	I _D = −2 A	
Gate to Drain charge	Qgd	_	1.2	_	nC		
Turn - on delay time	$t_{d(on)}$	_	20	_	ns	$V_{DS} = -10 \text{ V}, V_{GS} = -10 \text{ V}$	
Rise time	t _r	_	25	_	ns	$I_D = -1 A, R_L = 10 \Omega,$	
Turn - off delay time	$t_{d(off)}$	_	37	_	ns	$R_g = 4.7 \Omega$	
Fall time	t _f	_	4	_	ns		
Body - Drain diode forward voltage	V_{DF}	_	-0.85	-1.2	V	$I_F = -2 A, V_{GS} = 0$	

Notes: 3. Pulse test

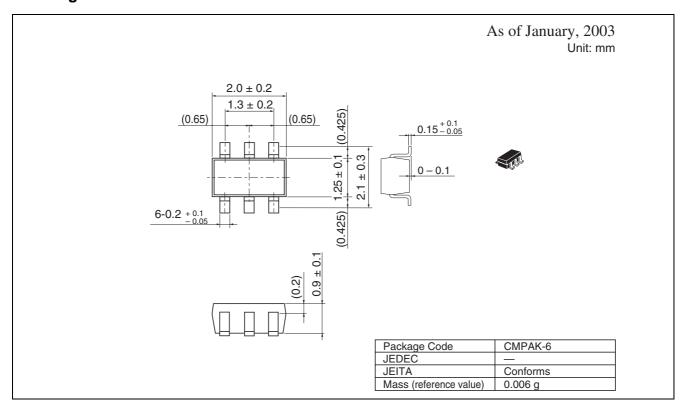
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT1111C-EL-E	3000 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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